

7 September 2004

Docket: 21295.73 (H5749US)

Patent Application Data Sheet--Bibliographic Data

**Supplemental Application Data Sheet****Application Information**

Application Number::	not assigned
Filing Date::	not assigned
Application Type::	Regular
Subject Matter::	Utility
Suggested Classification::	
Suggested Group Art Unit::	
Title::	Method and Apparatus for Scanning a Semiconductor Wafer
Attorney Docket Number::	21295.73 (H5749US)
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	3
Total Drawing Sheets::	3
Small Entity?::	No
Licensed US Govt. Agency::	
Contract or Grant Numbers::	
Secrecy Order in Parent Appl.?::	

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Germany
Status::	Full Capacity
Given Name::	Detlef
Middle Name::	
Family Name::	Michelsson
Name Suffix::	
City of Residence::	Wetzlar-Naunheim
State or Province of Residence::	
Country of Residence::	Germany
Street of mailing address::	Sonnenstrasse 20
City of mailing address::	Wetzlar-Naunheim
State or Province of mailing address::	
Country of mailing address::	Germany
Postal or Zip Code of mailing address::	D-35584

Correspondence Information

Correspondence Customer Number::	029127
----------------------------------	--------

Representative Information

Patent Application Data Sheet--Bibliographic Data

Representative Customer Number::	029127
----------------------------------	--------

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Germany	DE10307358.2-52	02/21/2003	Yes

Assignee Information

Assignee Name::	<u>Leica Microsystems Semiconductor GmbH</u>
Street of mailing address::	<u>Ernst-Leitz-Strasse 17-37</u>
City of mailing address::	<u>Wetzlar</u>
State or Province of mailing address::	<u>MA</u>
Country of mailing address::	<u>Germany</u>
Postal or Zip Code of mailing address::	<u>D-35578</u>